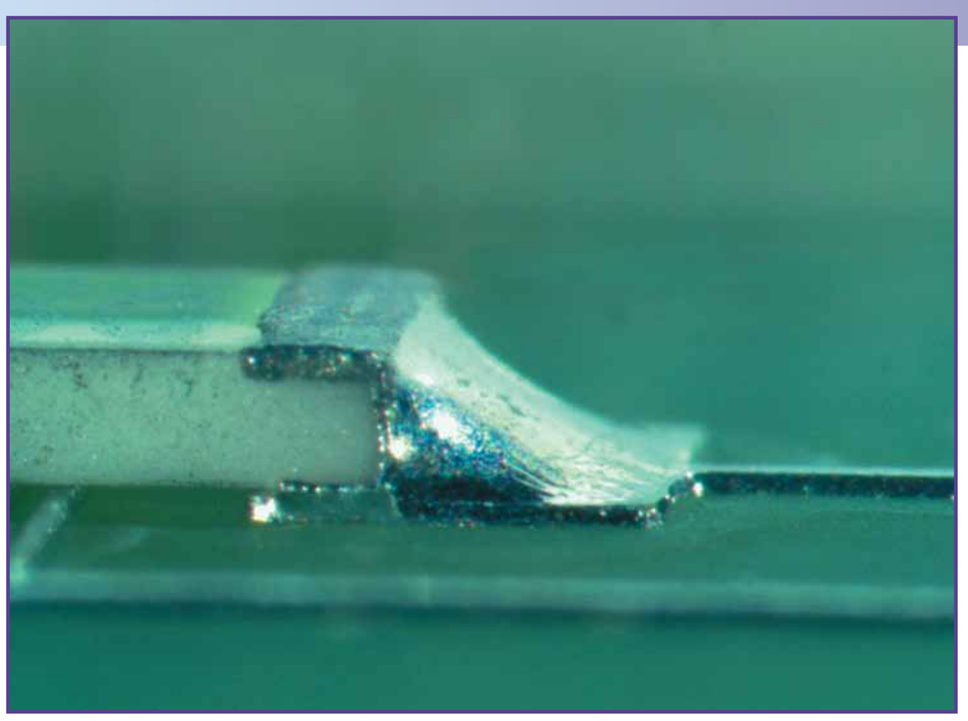
Chip Components • Class 2

Target Condition

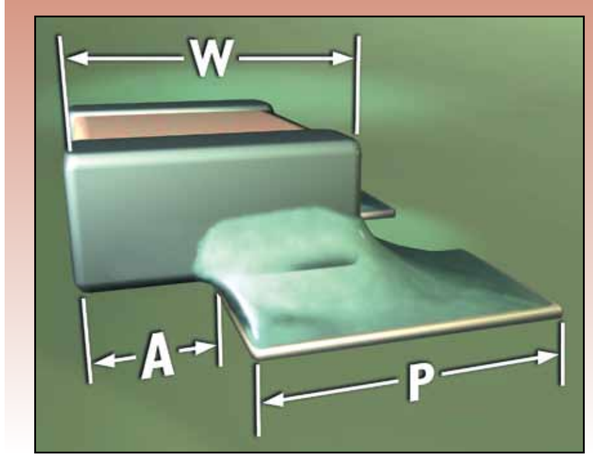


This photo represents an ***ideal*** surface mount solder joint for any class of rectangular Chip component.

The following illustrations show the ***limits*** of component misalignment and solder joint size. Solder joints that ***do not meet*** any of these conditions for 1, 3 or 5-sided terminations should be considered ***unacceptable***.

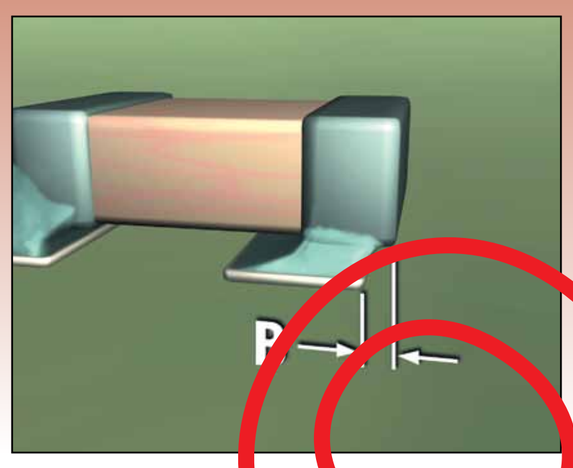
Notes: Solder joints are semi-transparent to show relationship between land and termination. Minimum side joint length, dimension **(D)**, is not required for chips, only a properly wetted fillet.

Acceptability Requirements



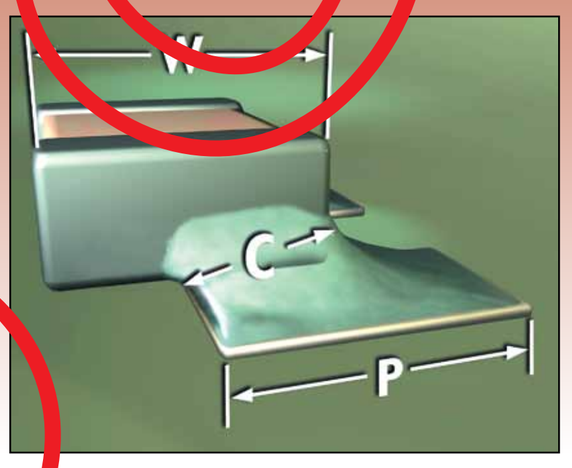
Side Overhang (A)

The component may overhang the side of the land a **maximum** of 50% of the width of the component termination **(W)**, or 50% of the width of the land **(P)**, whichever is less.



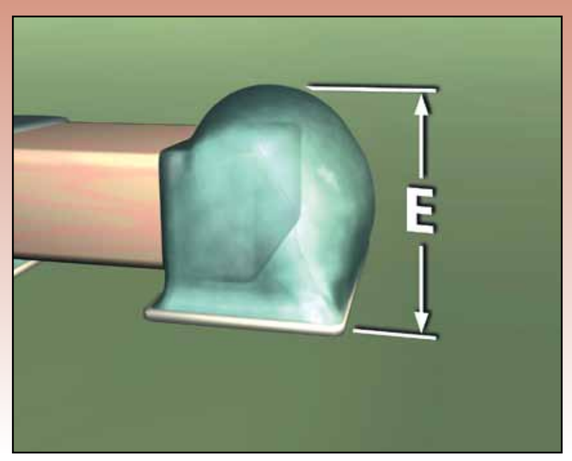
End Overhang (B)

Any part of the component termination extending beyond the land is **unacceptable.**



End Joint Width (C)

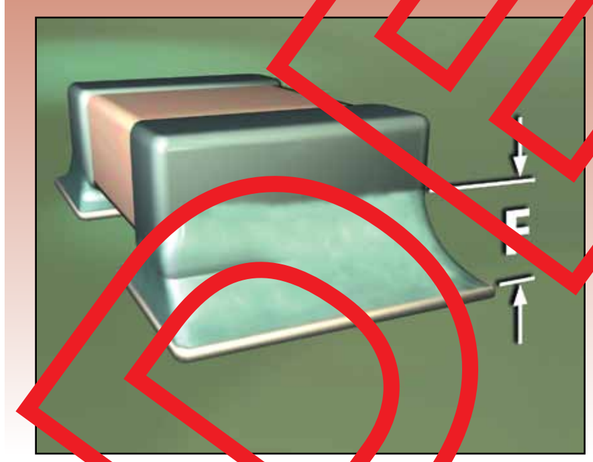
The width of the solder joint at its narrowest point must be a **minimum** of 50% the width of the component termination **(W),** or 50% of the width of the land **(P),** whichever is less.



Fillet Height (E)

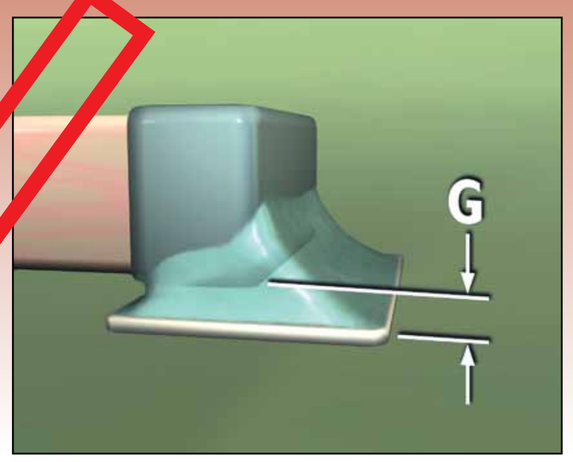
The solder may overhang the land, and extend onto the top of the termination, but **not touch** the top of the component body, as a **maximum** fillet height.

Acceptability Requirements



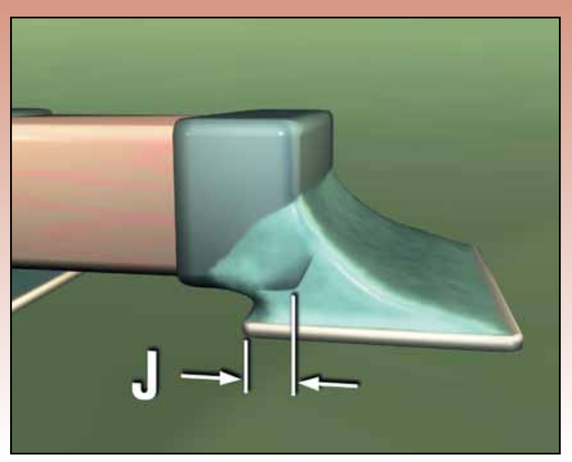
Fillet Height (F)

Wetting is evident on termination's vertical surfaces as a **minimum** fillet height.



Solder Thickness (G)

The **minimum** distance between the land and component termination is **not specified.** Only a properly wetted fillet must be evident.



End Overlap (J)

Some amount of overlap between the component termination and the land is **required** for **minimum** acceptance.

References:
IPC-A-610**E** and
IPC J-STD-001**E**

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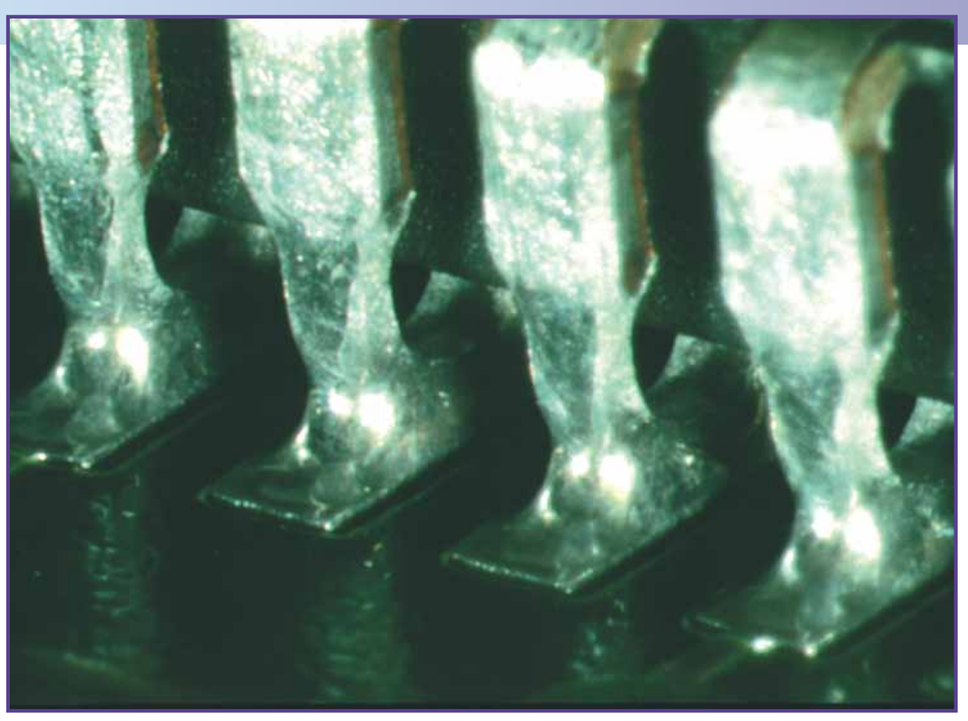
J-Lead Components • Class 2

Target Condition

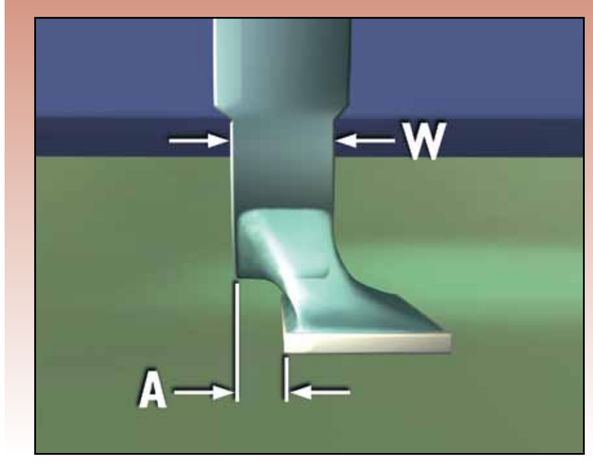


This photo represents an ***ideal*** surface mount solder joint for any class of J-Lead component.

The following illustrations show the ***limits*** of component misalignment and solder joint size. Solder joints that ***do not meet*** any of these conditions should be considered ***unacceptable.***

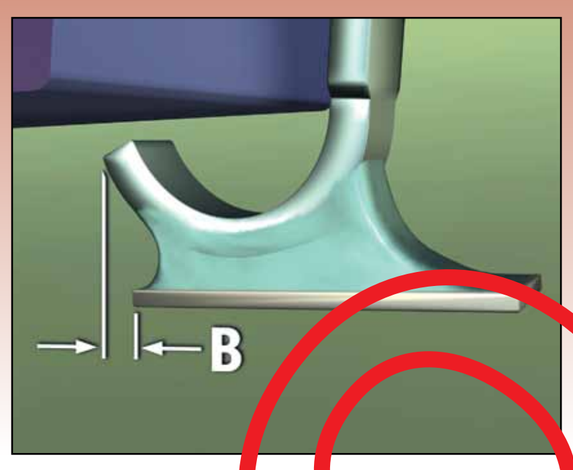
Note: Solder joints are semi-transparent to show relationship between land and lead.

Acceptability Requirements



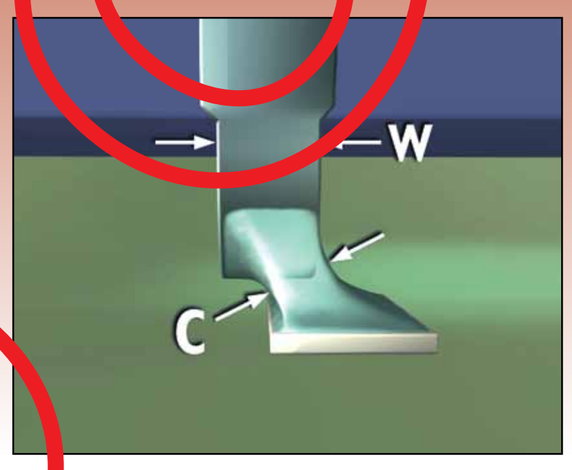
Side Overhang (A)

The component lead may overhang the side of the land a **maximum** of 50% of the width of the lead **(W)**.



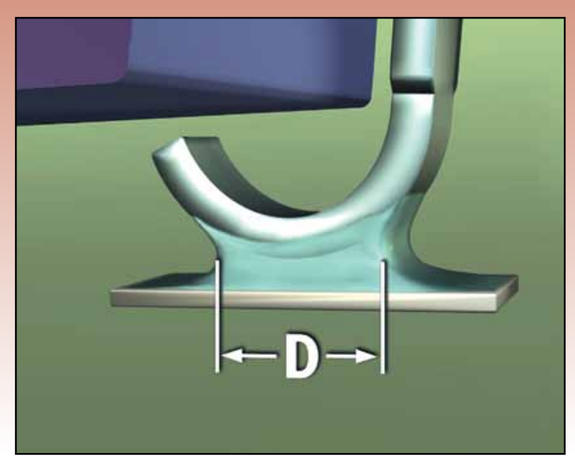
Toe Overhang (B)

The **maximum** distance the end, or tip, of the lead may extend over the edge of the land is **not specified.**



End Joint Width (C)

The width of the solder joint at its narrowest point needs to be a **minimum** of 50% the lead width **(W).**



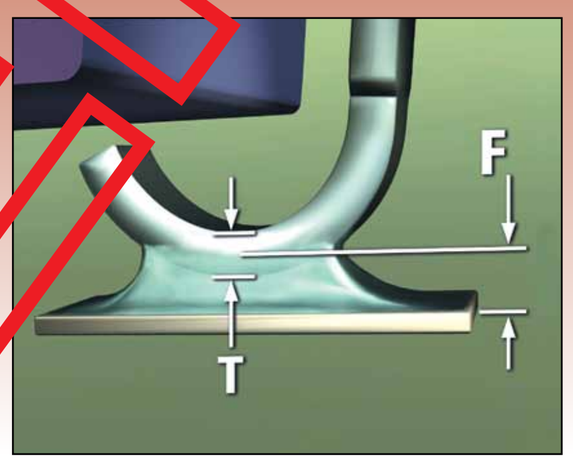
Side Joint Length (D)

The length of the solder joint at its narrowest point must be a **minimum** of 150% the width of the lead **(W).**

Acceptability Requirements

Fillet Height (E)

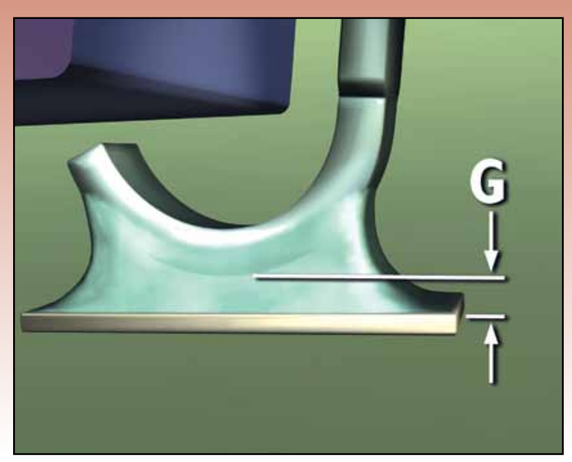
The solder may **not touch** the component body as a **maximum** fillet height.



Heel Fillet Height (F)

The heel fillet must extend at least 50% the thickness of the component lead **(T)*,** as a **minimum** fillet height.

** Including any measurement for solder thickness **(G)**.*



Solder Thickness (G)

The **minimum** distance between the land and component lead is **not specified.** Only a properly wetted fillet must be evident.

References:
IPC-A-610**E** and
IPC J-STD-001**E**

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Target Condition

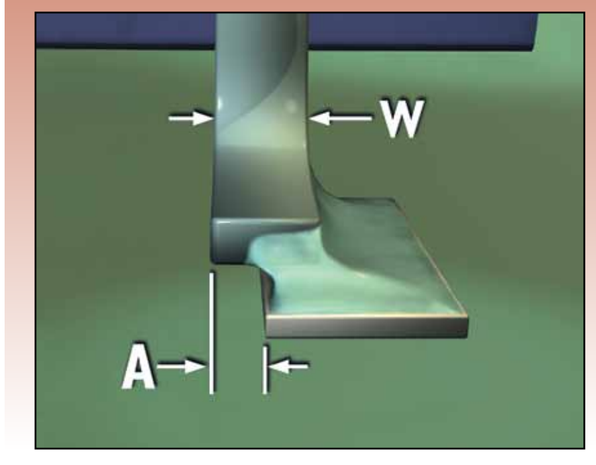
Gull Wing Components – Class 2

This photo represents an ***ideal*** surface mount solder joint for any class of Gull Wing component.

The following illustrations show the ***limits*** of component misalignment and solder joint size. Solder joints that ***do not meet*** any of these conditions should be considered ***unacceptable***.

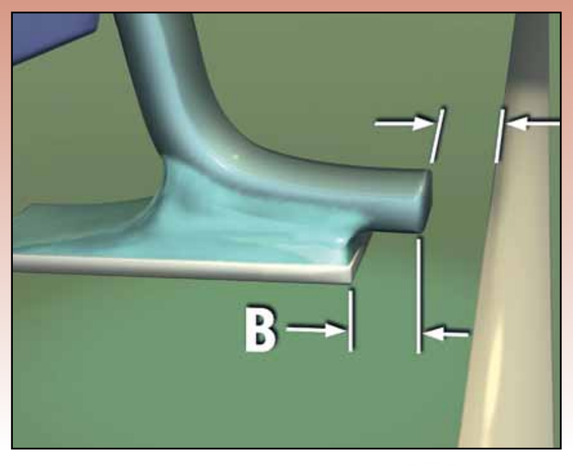
Note: Solder joints are semi-transparent to show relationship between land and lead.

Acceptability Requirements



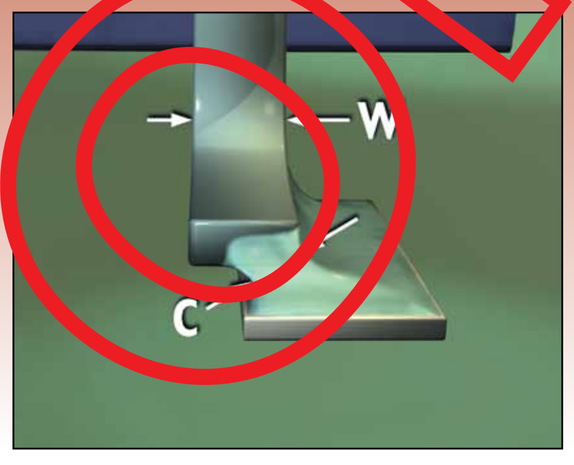
Side Overhang (A)

The component lead may overhang the side of the land a **maximum** of 50% of the width of the lead **(W),** or 0.5 mm (0.02 in.), whichever is less.



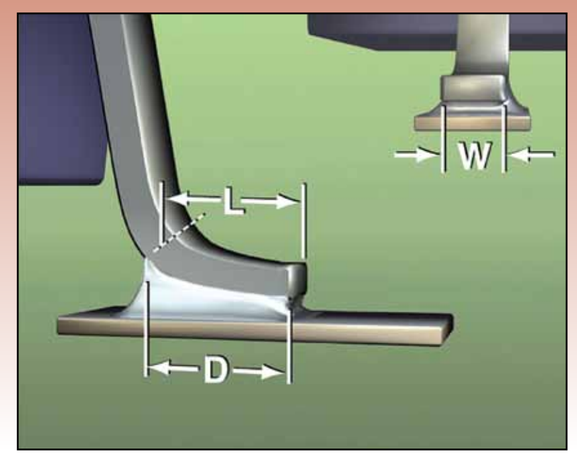
Toe Overhang (B)

The end or tip of the lead extending over the edge of the land must not violate minimum electrical clearance as a **maximum** condition.



End Joint Width (C)

The width of the solder joint at its narrowest point needs to be at least 50% the lead width **(W),** as a **minimum** requirement.

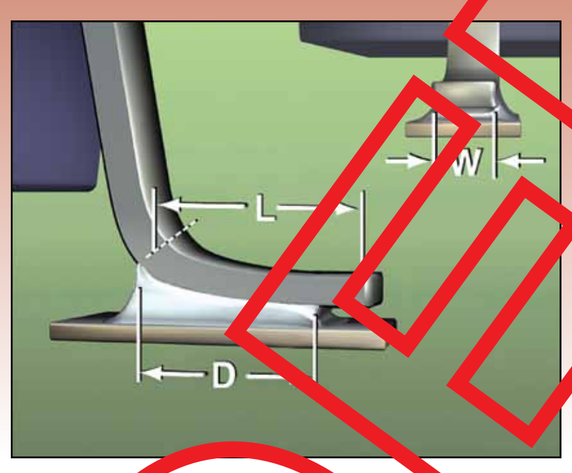


Side Joint Length (D)

Short Foot—If foot length **(L)** is less than 3 **(W),** then **minimum (D)** is 100% **(L).**

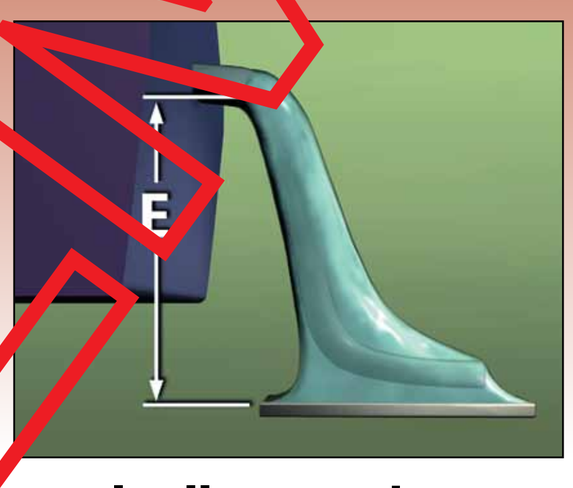
Note: *Fine pitch leads—short and long foot—require* **(D)** *to be at least 0.5 mm (0.02 in.).*

Acceptability Requirements



Side Joint Length (D)

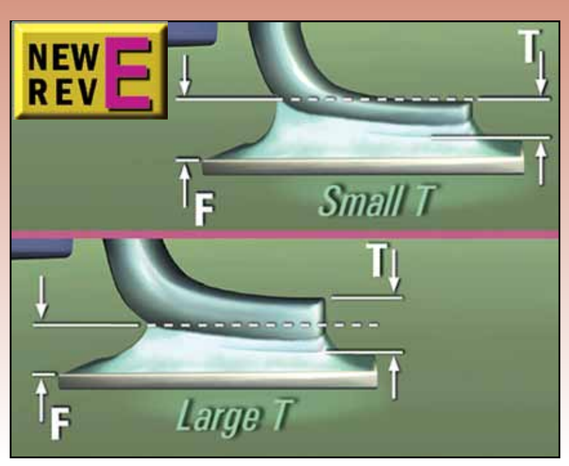
Long Foot—When foot length **(L)** is equal to or greater than three lead widths **(W),** side joint length **(D)** must be a **minimum** of 3 **(W)** or 75% **(L),** whichever is longer.



Heel Fillet Height (E)

Solder may extend to the top bend of the lead, or knee, but **not touch** the component body or end seal as a **maximum** fillet height.

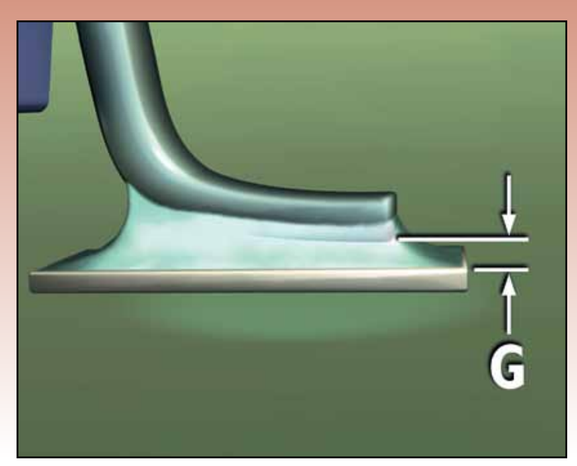
Note: *Solder may touch the body of a plastic SOIC or SOT Component.*



Heel Fillet Height (F)

Small T: Where lead thickness **(T)** is 0.38 mm or less, **minimum** heel fillet height is equal to **(T)***, measured at the toe.

Large T: Where **(T)** is greater than 0.38 mm, Dim. F is a **minimum** of 50% **(T)***.



Solder Thickness (G)

The **minimum** distance between the land and component lead is **not specified**. Only a properly wetted fillet must be evident.

** Including any measurement for solder thickness* ***(G)****.*

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IPC J-STD-001**E**